

# **CHEMICAL TINNING PLANT | BUNGARD PROTEC SN**



**SKU: PROTEC-SN** 



#### **BUNGARD PROTEC 2030/2040**

PROTEC SN – Professional equipment for the **production of final surfaces on printed circuit boards**. The machine includes all the necessary tanks and electrical equipment in a very compact design.

#### Available models:

### PROTEC 2030

Max. board size: 200 x 300 mm

Teflon heating elements: 2 pieces x 400W

Tank volume: 10L

Dimensions (LxWxH): ca. 790 x 710 x 1160 mm

Power supply: Single-phase 230V, AC.

PROTEC 3040

Max. board size: 300 x 400 mm

Teflon heating elements: 2 pieces x 800W

Tank volume: 20L

Dimensions (LxWxH): ca. 790 x 810 x 1160 mm

Power supply: Single-phase 230V, AC.



#### **Features**

- TANK 1 | Microetch With ball cock outlet valve, cover, timer
- TANK 2 | Spray / Rinsing Regulated by an angle seat solenoid valve, with ball cock outlet valve
- TANK 3 | Organic metal With ball cock outlet valve, cover, timer
- TANK 4 | Chemical tin 7001 With PTFE heating element thermostatically regulated 20-80°C, ball cock outlet valve, cover, timer
- TANK 5 | Warm rinsing With stainless steel heating element thermostatically regulated 20-50°C, ball cock outlet valve, cover, timer
- Underframe (plastic), control unit with main switch
- PCB holder.

## **Advantages**

Tin layers which have been created with the Protec ORMECON® process guarantee:

- Planar surface for SMD technology
- Pure tin deposit, even with high copper load of the bath
- Significant reduction of diffusion velocity
- Possibility of multiple soldering, even with intermediate storage
- Improved temperature resistance.

The design of PROTEC SN allows easy modifications. By **adding or skipping tanks** you can adapt the PROTEC to the requirements of the following processes:

- Electroless Nickel / Electroless Gold
- OSP (Organic Solderability Preservative).